

# EMRC12F1H-30.720M

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## REGULATORY COMPLIANCE (Data Sheet downloaded on Jun 2, 2020)


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## ITEM DESCRIPTION

MEMS Clock Oscillators LVPECL (PECL) 2.5Vdc 6 Pad 5.0mm x 7.0mm Plastic Surface Mount (SMD) 30.720MHz  $\pm$ 20ppm over 0°C to +70°C

## ELECTRICAL SPECIFICATIONS

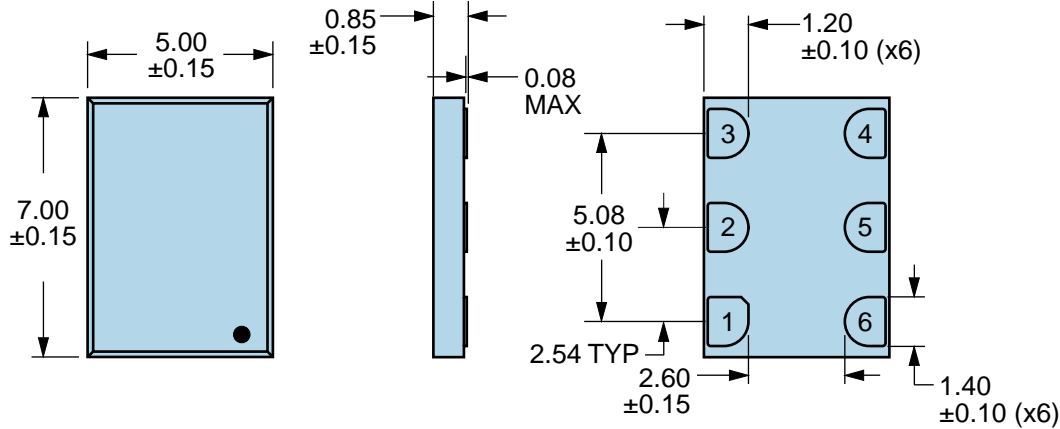
Nominal Frequency	30.720MHz
Frequency Tolerance/Stability	$\pm$ 20ppm Maximum over 0°C to +70°C (Inclusive of all conditions: Calibration Tolerance at 25°C, Frequency Stability over the Operating Temperature Range, Supply Voltage Change, Output Load Change, 1st Year Aging at 25°C, Reflow, Shock, and Vibration)
Aging at 25°C	$\pm$ 1ppm Maximum First Year
Supply Voltage	2.5Vdc $\pm$ 10%
Input Current	60mA Typical, 70mA Maximum (Excluding Load Termination Current)
Output Voltage Logic High (Voh)	Vdd -1.10Vdc Minimum, 1.60Vdc Typical, Vdd -0.70Vdc Maximum
Output Voltage Logic Low (Vol)	Vdd -1.90Vdc Minimum, 0.80Vdc Typical, Vdd -1.50Vdc Maximum
Rise/Fall Time	300pSec Typical, 500pSec Maximum (Measured over 20% to 80% of waveform)
Duty Cycle	50 $\pm$ 10(%) (Measured at 50% of waveform)
Output Swing (VOpp)	600mVdc Minimum, 800mVdc Typical, 1000mVdc Maximum
Load Drive Capability	50 Ohms into Vcc-2.0Vdc
Output Logic Type	LVPECL
Logic Control / Additional Output	Output Enable (OE) and Complementary Output
Output Control Input Voltage	Vih of 70% of Vdd Minimum or No Connect to Enable Output and Complementary Output, Vil of 30% of Vdd Maximum to Disable Output and Complementary Output (High Impedance)
Output Enable Current	35mA Maximum (OE) Without Load
RMS Phase Jitter	0.5pSec Typical, 1pSec Maximum (Fj = 12kHz to 20MHz; Random)
Period Jitter (Deterministic)	0.2pSec Typical
Period Jitter (Random)	1.0pSec Typical
Period Jitter (RMS)	1.4pSec Typical, 1.7pSec Maximum
Period Jitter (pk-pk)	15pSec Typical, 20pSec Maximum
Start Up Time	10mSec Maximum
Storage Temperature Range	-55°C to +125°C

## ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

ESD Susceptibility	MIL-STD-883, Method 3015, Class 2, HBM 2000V
Flammability	UL94-V0
Mechanical Shock	MIL-STD-883, Method 2002, Condition G, 30,000G
Moisture Resistance	MIL-STD-883, Method 1004
Moisture Sensitivity Level	J-STD-020, MSL 1
Resistance to Soldering Heat	MIL-STD-202, Method 210, Condition K
Resistance to Solvents	MIL-STD-202, Method 215
Solderability	MIL-STD-883, Method 2003 (Six I/O Pads on bottom of package only)
Temperature Cycling	MIL-STD-883, Method 1010, Condition B
Thermal Shock	MIL-STD-883, Method 1011, Condition B
Vibration	MIL-STD-883, Method 2007, Condition A, 20G

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### MECHANICAL DIMENSIONS (all dimensions in millimeters)

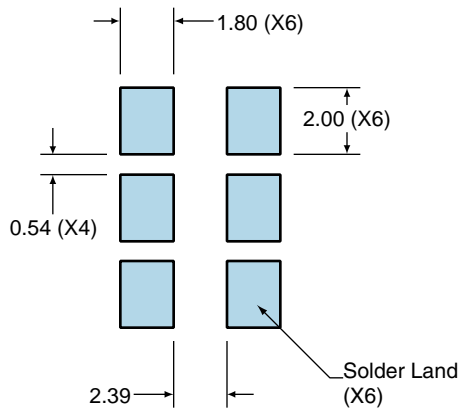


PIN	CONNECTION
1	Output Enable (OE)
2	No Connect
3	Case Ground
4	Output
5	Complementary Output
6	Supply Voltage

LINE	MARKING
1	XXXXXX XXXXXX=Ecliptek Manufacturing Lot Code

### Suggested Solder Pad Layout

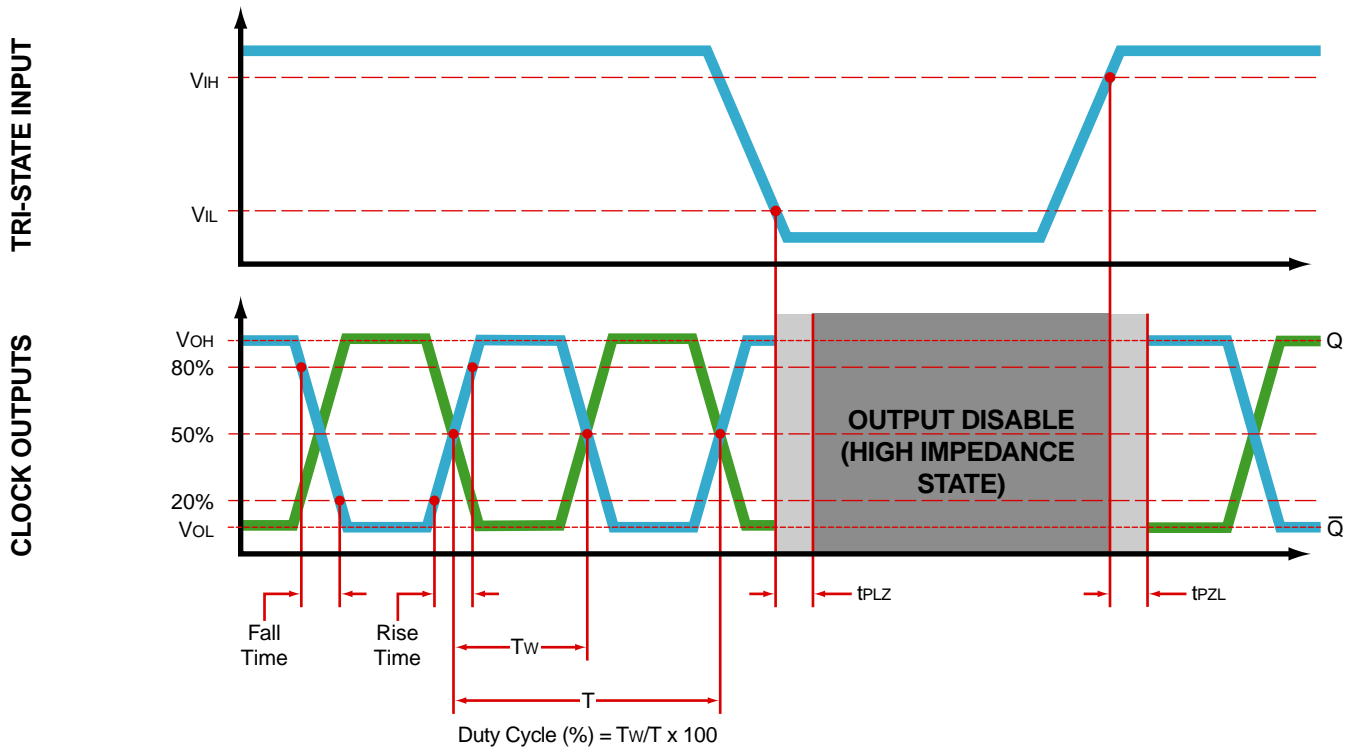
All Dimensions in Millimeters



All Tolerances are ±0.1

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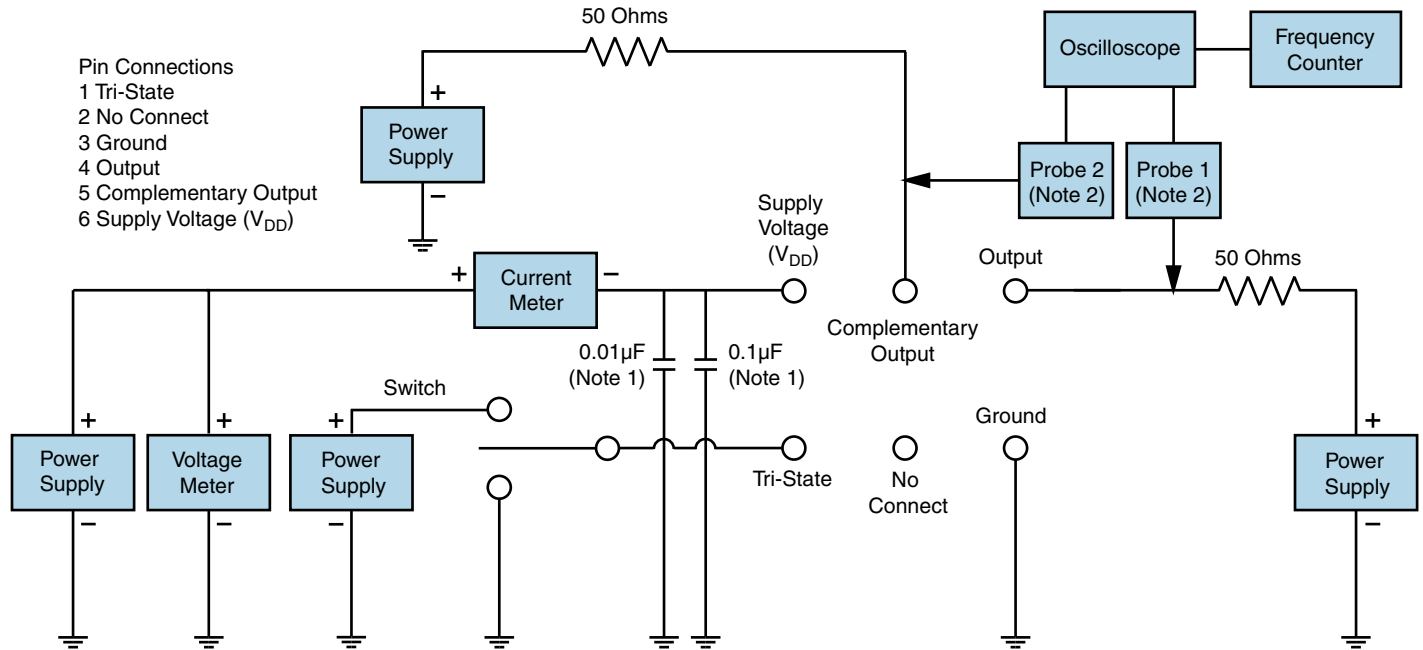
## OUTPUT WAVEFORM & TIMING DIAGRAM



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## Test Circuit for Tri-State and Complementary Output



Note 1: An external  $0.01\mu\text{F}$  ceramic bypass capacitor in parallel with a  $0.1\mu\text{F}$  high frequency ceramic bypass capacitor close (less than 2mm) to the package ground and supply voltage pin is required.

Note 2: A low capacitance ( $<12\text{pF}$ ), 10X attenuation factor, high impedance ( $>10\text{Mohms}$ ), and high bandwidth ( $>500\text{MHz}$ ) passive probe is recommended.

Note 3: Test circuit PCB traces need to be designed for a characteristic line impedance of 50 ohms.

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## Recommended Solder Reflow Methods



### High Temperature Infrared/Convection

<b>Ts MAX to TL (Ramp-up Rate)</b>	3°C/Second Maximum
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#### Preheat

- Temperature Minimum (Ts MIN)	150°C
- Temperature Typical (Ts TYP)	175°C
- Temperature Maximum (Ts MAX)	200°C
- Time (ts MIN)	60 - 180 Seconds

<b>Ramp-up Rate (TL to TP)</b>	3°C/Second Maximum
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#### Time Maintained Above:

- Temperature (TL)	217°C
- Time (tL)	60 - 150 Seconds

<b>Peak Temperature (TP)</b>	260°C Maximum for 10 Seconds Maximum
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<b>Target Peak Temperature (TP Target)</b>	250°C +0/-5°C
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<b>Time within 5°C of actual peak (tp)</b>	20 - 40 Seconds
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<b>Ramp-down Rate</b>	6°C/Second Maximum
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<b>Time 25°C to Peak Temperature (t)</b>	8 Minutes Maximum
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<b>Moisture Sensitivity Level</b>	Level 1
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## Recommended Solder Reflow Methods



### Low Temperature Infrared/Convection 240°C

$T_s$ MAX to $T_L$ (Ramp-up Rate)	5°C/Second Maximum
<b>Preheat</b>	
- Temperature Minimum ( $T_s$ MIN)	N/A
- Temperature Typical ( $T_s$ TYP)	150°C
- Temperature Maximum ( $T_s$ MAX)	N/A
- Time ( $t_s$ MIN)	60 - 120 Seconds
<b>Ramp-up Rate (<math>T_L</math> to <math>T_P</math>)</b>	5°C/Second Maximum
<b>Time Maintained Above:</b>	
- Temperature ( $T_L$ )	150°C
- Time ( $t_L$ )	200 Seconds Maximum
<b>Peak Temperature (<math>T_P</math>)</b>	240°C Maximum
<b>Target Peak Temperature (<math>T_P</math> Target)</b>	240°C Maximum 2 Times / 230°C Maximum 1 Time
<b>Time within 5°C of actual peak (<math>t_p</math>)</b>	10 Seconds Maximum 2 Times / 80 Seconds Maximum 1 Time
<b>Ramp-down Rate</b>	5°C/Second Maximum
<b>Time 25°C to Peak Temperature (t)</b>	N/A
<b>Moisture Sensitivity Level</b>	Level 1

### Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum.

### High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum.